




<b>PCN Number:</b>	20190917001.1		<b>PCN Date:</b>	Sep 18, 2019				
<b>Title:</b>	Die Coating material change for Select Devices							
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services					
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Dec 18, 2019	<b>Estimated Sample Availability:</b>	Date provided at sample request.					
<b>Change Type:</b>								
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials			
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification			
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process			
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input checked="" type="checkbox"/>	Wafer Bump Process			
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process			
		<input type="checkbox"/>	Part number change					
<b>PCN Details</b>								
<b>Description of Change:</b>								
This notification is to announce the change to the Die Coating material for the selected devices listed in "Product Affected" section.								
Die coating material differences (on top of top thick copper metal layer) are noted below:								
<b>Change From</b>		<b>Change To</b>						
NONE		<b>POLYIMIDE</b>						
Die Revision: A		<b>Die Revision: D*</b>						
*No design change. Addition of Polyimide die coating only.								
Qual details are provided in the Qual Data Section.								
<b>Reason for Change:</b>								
Quality Improvement								
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>								
None								
<b>Changes to product identification resulting from this PCN:</b>								
The Die Rev designator will change as shown in the table and sample label below:								
<b>Current</b>		<b>New</b>						
Die Rev [2P]	<b>Die Rev [2P]</b>							
A	<b>D</b>							
Sample product shipping label (not actual product label)								
 MADE IN: Malaysia 2DC: 20: <table border="1" style="font-size: small;"> <tr> <td>MSL 2 / 260C / 1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 / 235C / UNLIM</td> <td>03/29/04</td> </tr> </table> OPT: ITEM: 39 <b>LBL: 5A (L)T0:1750</b>		MSL 2 / 260C / 1 YEAR	SEAL DT	MSL 1 / 235C / UNLIM	03/29/04	 		(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) OSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS
MSL 2 / 260C / 1 YEAR	SEAL DT							
MSL 1 / 235C / UNLIM	03/29/04							
<b>Product Affected Group:</b>								
UCC27201ADPRR	UCC27201ADPRT	UCC27201ADRRCR	UCC27201ADRCT					

## Qualification Report

### UCC27201A die with Polyimide coating (PI) Approve Date 12-Jun-2019

#### Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: UCC27201ADP R	Qual Device: UCC27201ADR C	QBS Product Reference: UCC27201ADP R	QBS Product Reference: UCC27201ADR CT	QBS Process Reference: UCC27201AQD DARQ1	QBS Process & Package Reference: UCC27201AQD MKRQ1	QBS Package Reference: TPA5050RSA	QBS Package Reference: TP561020DRC CU WIRE
AC	Autoclave 121C	96 Hours	-	-	3/231/0	3/231/0	3/231/0	3/231/0	-	3/231/0
CDM	ESD - CDM - Q100	1500 Volts	-	-	-	-	1/3/0	1/3/0	-	-
CDM	ESD CDM	+/- 250, 500V	-	-	1/3/0	1/3/0	-	-	-	-
DS	Die Shear	-	1/Pass	1/Pass	1/Pass	1/Pass	1/Pass	1/Pass	1/10/0	3/30/0
ED	Electrical Characterization	Per Datasheet Parameters	-	-	1/Pass	1/Pass	3/90/0	3/90/0	-	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	-	-	3/2400/0	-	-	-
HAS T	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	3/231/0	3/231/0	1/80/0	-
HBM	ESD - HBM - Q100	1000 Volts	-	-	-	-	1/3/0	1/3/0	-	-
HTO L	Life Test, 125C	1000 Hours	-	-	-	-	3/231/0	1/77/0	-	-
HTO L	Life Test, 140C	480 Hours	-	-	-	-	-	-	1/116/0	-
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	-	1/45/0	1/77/0	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	-	-	-	-	3/231/0
LU	Latch-up	(per AEC-Q100-004)	-	-	-	-	1/6/0	1/6/0	-	-

Type	Test Name / Condition	Duration	Qual Device: UCC27201ADP R	Qual Device: UCC27201ADR C	QBS Product Reference: UCC27201ADP R	QBS Product Reference: UCC27201ADR CT	QBS Process Reference: UCC27201AQD DARQ1	QBS Process & Package Reference: UCC27201AQD MKRQ1	QBS Package Reference: TPA5050RSA	QBS Package Reference: TP561020DRC CU WIRE
PD	Physical Dimensions	--	-	-	-	-	-	3/30/0	1/5/0	3/15/0
PTC	Power Temperature Cycle, -40/125C	1000 Cycles	-	-	-	-	1/45/0	-	-	-
TC	Temperature Cycle, -65/150C	1000 Cycles	-	-	-	-	-	-	-	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	3/231/0	3/231/0	3/231/0	3/231/0	-	3/261/0
TC-BP	Post TC Bond Pull	Wires	-	-	-	-	1/30/0	3/15/0	-	-
TS	Thermal Shock - 65/150C	1000 Cycles	-	-	-	-	-	-	-	3/231/0
TS	Thermal Shock - 65/150C	500 Cycles	-	-	-	-	-	-	-	3/231/0
WBP	Bond Pull	Wires	1/Pass	1/Pass	1/Pass	1/Pass	1/40/0	3/90/0	1/76/0	3/228/0
WBS	Bond Shear	Wires	1/Pass	1/Pass	1/Pass	1/Pass	1/40/0	3/90/0	1/76/0	3/228/0
YLD	Yield Evaluation	(per mfg. Site specification)	1/Pass	1/Pass	-	-	-	-	1/Pass	3/Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THBI/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

#### Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

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